

MISSION-CRITICAL  
INTERCONNECT  
SOLUTIONS



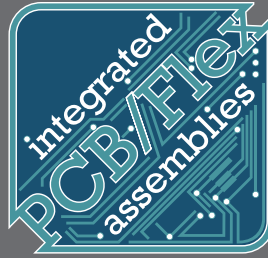
TURNKEY · CONNECTORIZED

# Integrated Flex, Rigid Flex, and Rigid PCB Assemblies

IPC-6012/6013 Specializing in Class III, Types 1-4 · Design, Prototyping, and Production

JUNE 2019

TURNKEY  
INTERCONNECT  
SYSTEMS/  
ASSEMBLIES



Flex, Rigid Flex, and Rigid PCB assemblies with signature interconnect technology available only from Glenair

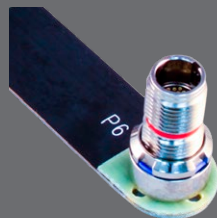


Turnkey connectorized flex, rigid flex, and rigid PCB assemblies incorporating Glenair's broad range of innovative small form-factor circular and rectangular PC-tail connector solutions. All terminations backpotted for compliance with conformal coating processes.

**GLENAIR SIGNATURE PC-TAIL CONNECTOR TYPES AVAILABLE IN TURNKEY FLEX ASSEMBLIES**



Series MWD Micro-D and innovative pogo-pin AlphaLink



Series 88 SuperFly



Series 79 Micro-Crimp



SuperSeal RJ45 and USB

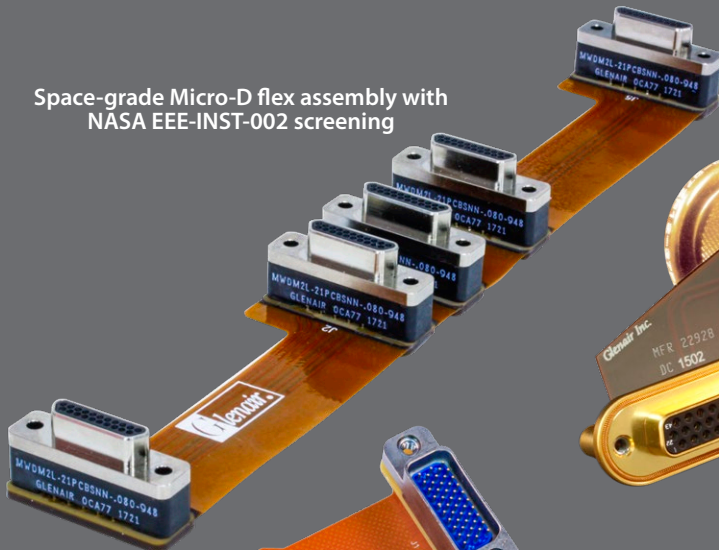
TURNKEY

# Flex, Rigid Flex, and Rigid PCB Assemblies with Glenair signature PC tail connectors



## MULTIBRANCH FLEX / PCB ASSEMBLIES WITH GLENAIR SIGNATURE CONNECTORS

Space-grade Micro-D flex assembly with NASA EEE-INST-002 screening



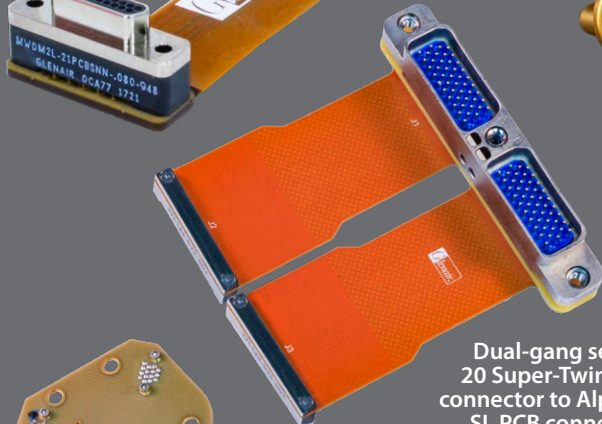
High-shock matched-impedance Mighty Mouse assembly with flex circuit



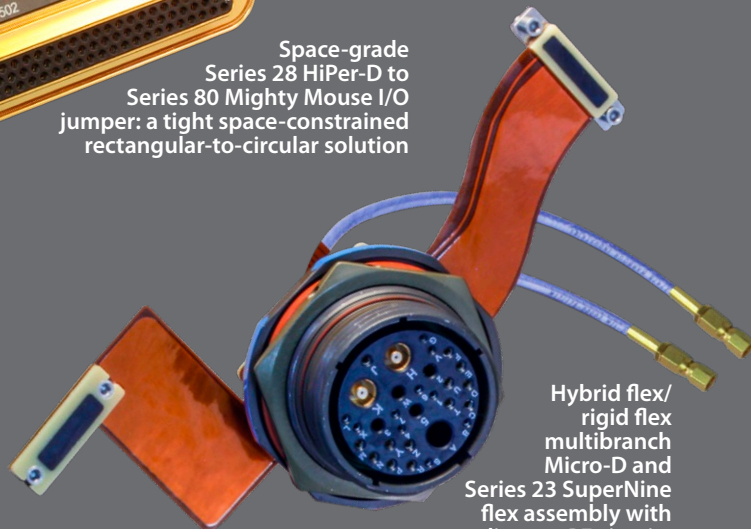
Space-grade Series 28 HiPer-D to Series 80 Mighty Mouse I/O jumper: a tight space-constrained rectangular-to-circular solution



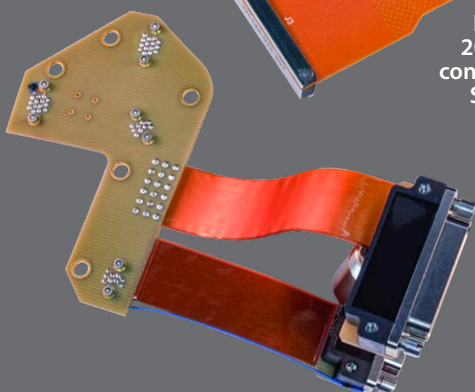
Dual-gang series 20 Super-Twin™ I/O connector to AlphaLink SL PCB connector



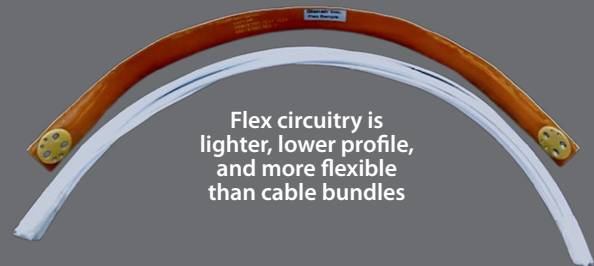
Hybrid flex/rigid flex multibranch Micro-D and Series 23 SuperNine flex assembly with discrete RF circuits



Stacked Micro-D I/O connectors with flex jumper to rigid PCB assembly

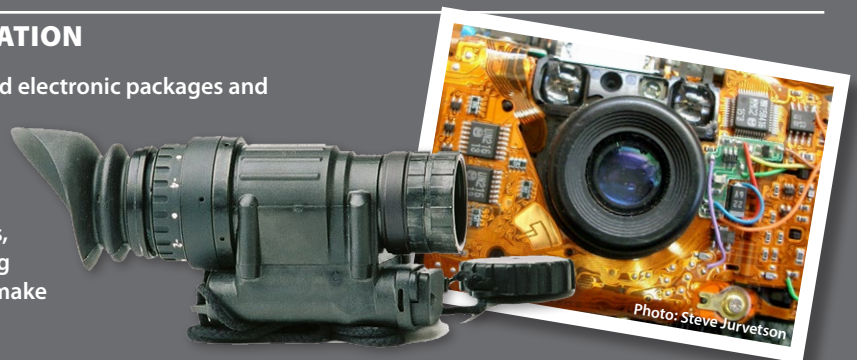


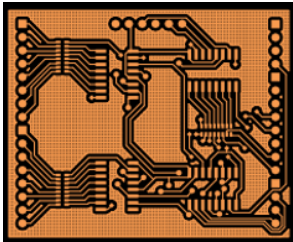
Flex circuitry is lighter, lower profile, and more flexible than cable bundles



## CONVENIENT PACKAGING AND INTEGRATION

Flex circuit assemblies are ideal for space-constrained electronic packages and enclosures, or for interconnect systems that are required to flex in 3 axes during normal use. Flex circuitry offers complete freedom to design boards and wiring for even the most densely-packed electronic enclosures. In mission-critical applications, the ability to reduce or even eliminate discrete wiring and boards in favor of flex circuitry helps designers make the most efficient use of available space.





## SPECIFICATION STANDARDS

The following tables describe, in brief, Glenair flex and rigid flex manufacturing formats and specifications. Glenair recommends commercial customers understand and adhere to IPC-6012/6013 specification standards which are fully supported by Glenair. Military customers may alternatively cite specifications IAW MIL-PRF-31032.

\* Information below is based on the most common materials and physical property requirements. Please consult the factory for alternatives

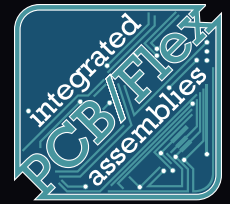
### Flex Assemblies

<b>Design Formats</b>	PADS • PADS PRO • Pro E / Creo • SolidWorks • Autodesk Inventor • CAM 350 • Altium • Valor • POLAR • XPedition
<b>Manufacturing Formats</b>	DXF • Gerber • ODB++ • IPC 2581
<b>Layer Count</b>	Max typ. up to 8
<b>Termination</b>	Thru hole • Reverse bare • Floating fingers / Sculpted circuits • ZIF Termination
<b>Conductor Width/Space</b>	Lines: .003" • Spacing: .003" (dependent on copper weight)
<b>Bend Radius (military)</b>	Single Metal Layer: 4–6X overall flex thickness • Double Metal Layers: 6–10X overall flex thickness • Multi Layer Metal: 12–15X overall flex thickness
<b>Materials / Tg</b>	Substrate: DuPont™ Kapton® polyimide flex adhesive and adhesiveless -60°C to 125°C Cover layer: DuPont™ Kapton® Stiffener: FR4 or DuPont™ Kapton® (metal stiffeners available upon request) Conductor: Copper, Aluminum, SS, Constantan High-temperature materials available
<b>Surface Finish</b>	ENIG • HASL • Immersion Tin and Silver • Soft and Hard Gold
<b>Specs and Quality Management</b>	IPC-6013 Class I, II, III, types 1-3 • ISO 9001, AS 9100

### Rigid Flex Assemblies

<b>Design Formats</b>	PADS • PADS PRO • Pro E / Creo • SolidWorks • Autodesk Inventor • CAM 350 • Altium • Valor • POLAR • XPedition
<b>Manufacturing Formats</b>	DXF • Gerber • ODB++ • IPC 2581
<b>Max Panel Thickness</b>	Range of thicknesses from .010" to as thick as .250"
<b>Layer Count</b>	27 +
<b>Via Technology</b>	Blind, buried • Thru hole • Filled (conductive and non-conductive)
<b>Conductor Width/Space</b>	Lines: .003" • Spacing: .003" (dependent on copper weight)
<b>Materials / Tg</b>	Substrate: Nelco 4000, Rogers, Megtron, Polyimide, and more
<b>Surface Finish</b>	ENIG • HASL • Immersion Tin and Silver • Soft and Hard Gold
<b>Specs and Quality Management</b>	IPC-6013 Class I, II, III, type 4 • ISO 9001, AS 9100, J-STD-001 Space

*DuPont™ and Kapton® are trademarks or registered trademarks of E.I. du Pont de Nemours and Company.*



### STANDARD DESIGN OPTIONS FOR INTEGRATED (CONNECTORIZED) FLEX/RIGID FLEX ASSEMBLIES

Properly designed flex and rigid flex assemblies offer significant space and weight savings compared to wire harnesses. Many design options are available, including integrated stiffeners, shielding, factory forming, selective bonding, termination, layer count and so on.

- 1 Right-angle surface mount Nanominiature plug connector
- 2 Hatch shield and solid copper shield flex
- 3 Series 801 Mighty Mouse receptacle with PC tails
- 4 AlphaLink® SL spring-loaded contact connector
- 5 Cross-hatch shield flex
- 6 Board-mount transceiver
- 7 Series 79 Micro-Crimp® right-angle PCB panel-mount receptacle
- 8 Solid copper shield flex

- 9 Micro-D 37-pin connector
- 10 Silver paste shield flex
- 11 Resistor, inductor, and capacitor
- 12 Series 88 SuperFly™ rear panel mount PCB receptacle
- 13 Black EMI film (suitable for commercial applications)
- 14 D38999 Series II type hermetic PC tail receptacle connector
- 15 ZIF (Zero Insertion Force) termination
- 16 6-layer rigid flex circuit board with BGA
- 17 Overmolded termination

### GROUND PLANES AND SHIELDS

Managing EMI emissions and signal line impedance are critical aspects of flex circuit design. Effective use of ground / shield planes, appropriate connector interfaces, and matched-impedance flex circuits delivers optimal high-speed signal integrity.

Full copper shield

Cross-hatch mesh shield

Hybrid solid/mesh

Black Tatsua and silver epoxy

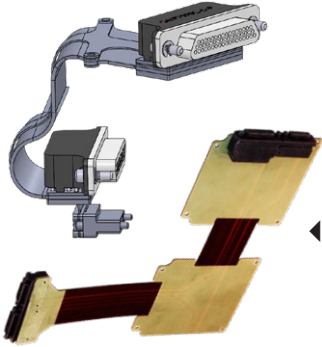
Connector-to-flex shielding (soldered pin insert)

Stitched vias

Polyimide-based for contact grounding



### MODELING AND 3-D PRINT RAPID PROTOTYPING



- 3-D representation of flex assemblies using SolidWorks
- 3-D printed “paper doll” outline mockups for fit checks with copper clad DuPont™ Kapton® to simulate actual flexibility
- Incorporation of customer-supplied wiring diagram and chassis information in laser-cut mechanical samples

◀ Example SolidWorks and 3-D printed paper doll prototype mockups produced by Glenair’s Integrated Flex Assembly team—typical turnaround 2–3 days upon receipt of request, unless extraordinary requirements are requested (e.g. loose leaf, cross-hatch shielding on 5+ layers)

▶ Here, a custom 3-D printed model is mated to a plug connector to check form and fit before actual part production

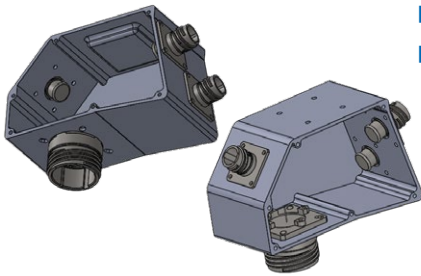


▲ Complimentary quick-turn mockups produced by by Glenair: 28-layer rigid flex (close-up and full-length), and 12-layer multibranch rigid flex



▲ HD Stacker board-to-board connector/flex mockup

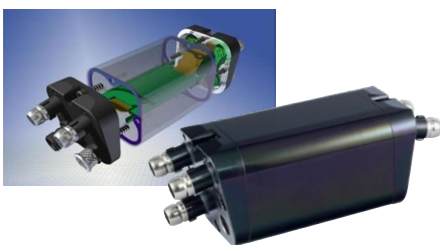
### SOLIDWORKS 3-D PROTOTYPING: “VIRTUAL” CONNECTOR MODIFICATIONS



- Customer-supplied STEP file of box with panel cutouts
- Glenair-supplied 3-D model of connector flange modifications

◀ In this example, customer supplied a STEP file of a box enclosure with panel cutouts. The Glenair engineering team used SolidWorks to design a specially-modified connector flange, allowing the customer to take advantage of our signature size-and weight-saving circular connector, the Series 80 Mighty Mouse.

### 3-D MODELING FOR CONNECTORIZED INTEGRATED SYSTEMS



- Turnkey connector manufacture and interconnect cable / flex harnessing
- Electronic box builds supported by software-based design and prototyping
- Turnkey integration of harness technologies, boxes, and mechanisms

◀ This integrated system enclosure, complete with printed circuitry, I/O connectors, and power modules was designed and modeled in SolidWorks prior to actual manufacture.

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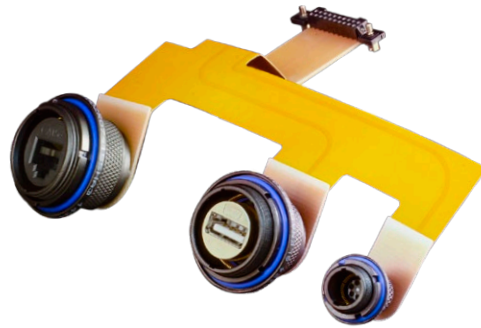




### FLEX AND RIGID FLEX DESIGN OPTIONS



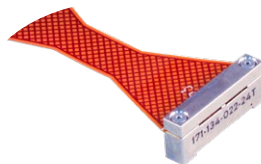
**Factory forming** facilitates assembly and helps the flex circuit adhere tightly to available space and routing



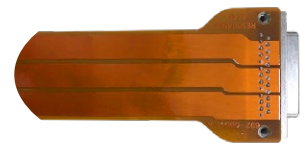
**Stiffeners incorporated into flex:** a practical approach for adding discrete mount points or component integration



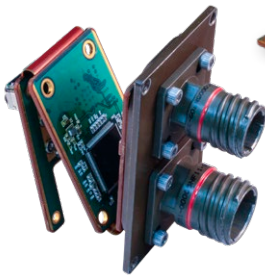
**Grounding** can be achieved by directly grounding the connector shell to flex circuitry as shown in the above example



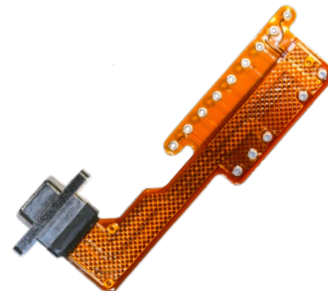
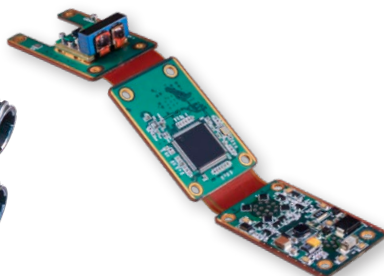
**EMI/RFI Shielding** is accomplished with solid or patterned shield planes, stitched vias, and/or with shielded I/O interconnects



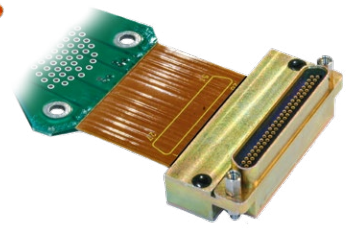
**High-Power** may be routed through flex circuitry with wider traces



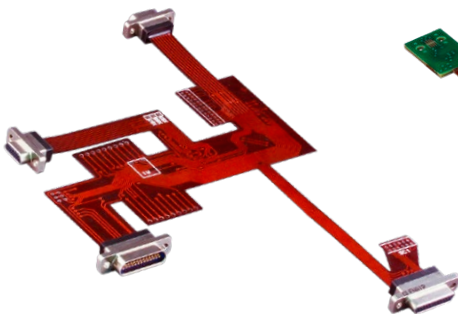
**Hybrid flex, rigid flex, and embedded PCB technology** facilitates electronic component size and weight reduction, and double-sided mounting of components



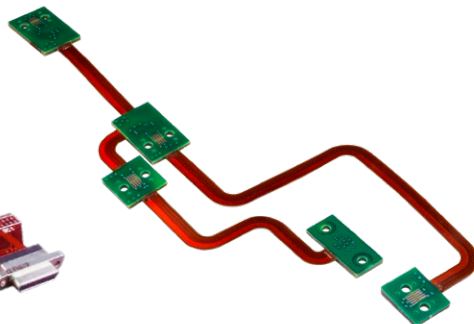
**Flex and rigid flex combination assemblies** provide hard mounting points and dynamic flexing and routing



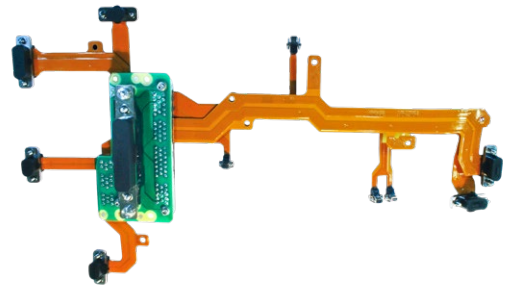
### MULTIBRANCH FLEX AND RIGID FLEX CONNECTORIZED ASSEMBLIES



**Micro-D** subminiature multibranch flex assembly—a Glenair specialty.



**Multibranch RJ45 / Ethernet / USB Flex** assembly

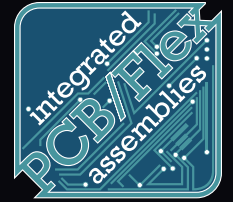


**High density .025"** contact center nanominiature multibranch flex assembly

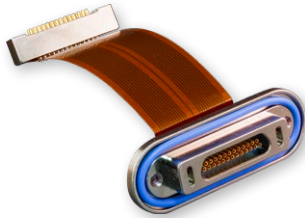


# RUGGEDIZED · HARSH-ENVIRONMENT Application / Design Options

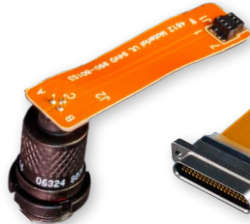
## Packaging for optimal form, fit, and function



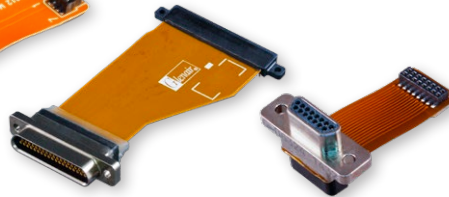
### POINT-TO-POINT CONNECTORIZED FLEX AND RIGID FLEX JUMPER DESIGN OPTIONS



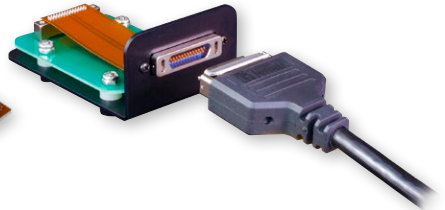
Environmentally sealed rectangular I/O interface flexi circuit



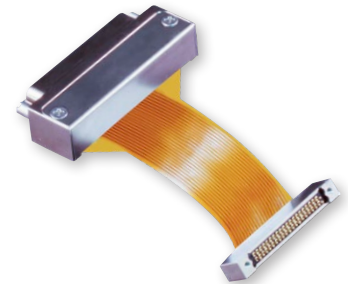
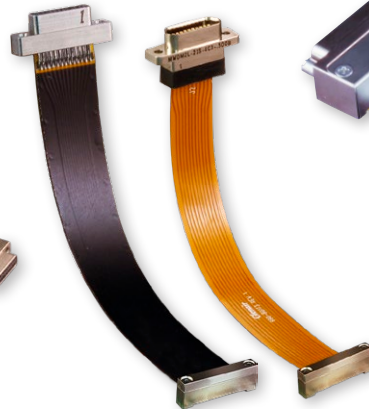
Military aerospace grade I/O connector to commercial-grade board level termination



Master-Latch quick disconnect Micro-D I/O flexi circuit

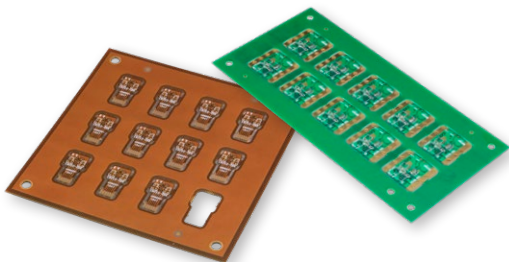


Military aerospace grade circular I/O connectors to matched impedance high-speed mil-aero board terminations



Military aerospace grade rectangular I/O connectors to matched impedance high-speed mil-aero board terminations

### SPECIAL-PURPOSE FLEX, RIGID-FLEX DESIGNS, AND PHOTONICFLEX CAPABILITIES



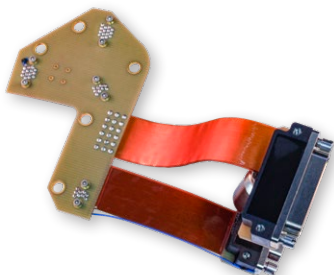
Production run of individual PCBs in panelized form



Space-grade Series 28 HiPer-D to Series 80 Mighty Mouse I/O jumper



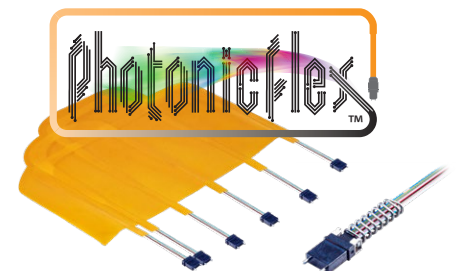
High-shock matched-impedance Mighty Mouse assembly with flex circuit



Stacked Micro-D I/O connectors with flex jumper to rigid PCB assembly



EMI/RFI filtered power transmission flex circuit assembly



PhotonicFlex circuitry for lightweight, small form-factor management of fiber optic media and MT ribbon terminations

TURNKEY

# Flex, Rigid Flex, and Rigid PCB Assemblies

## Interconnect I/O and termination design guide



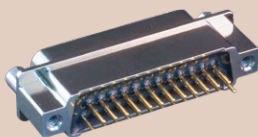
PARYLENE  
COMPATIBLE

First step in securing a time and delivery quote from Glenair is to communicate basic information regarding the flex assembly, including quantity requirements, number of layers, overall size, special features such as factory forming, stiffeners and so on. Accordingly, here is a five step flex design guide, beginning with I/O interconnect selection.

Note: all Glenair PCB I/O connectors are potted/sealed and certified parylene compatible.

### STEP 1: SELECT FLEX/RIGID FLEX ASSEMBLY I/O CONNECTOR(S)

HiPer-D 24308 is a high-performance, precision machined, shielded alternative to commercial-grade D-subminiatures

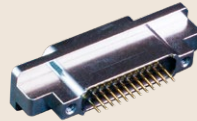


HiPer-D 24308  
straight and 90°



HiPer-D Combo  
straight and 90°

Series 79 Micro-Crimp is Glenair's high-density .075" contact center crimp- and shielded-contact, mil-aero grade rectangular



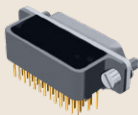
straight and 90° PC tail  
panel plugs and  
receptacles



high-speed datalink  
and rack-and-panel  
versions



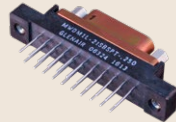
Series MWDM (MIL-DTL-83513) high-density microminiature .050" contact spacing mil-aero grade Micro-D subs



condensed-  
pitch board  
terminations/  
compact flange

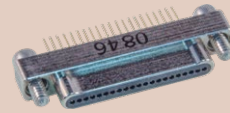


surface  
mount

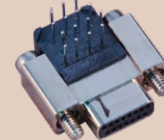


vertical and  
90° thru-hole

Series 89 (MIL-DTL-32139) ultra high-density .025" contact spacing mil-aero grade nanominiature



single-row vertical PCB  
plugs / receptacles



dual-row right  
angle PCB plugs /  
receptacles

SuperNine "better than QPL" advanced performance D38999 Series III type connectors



SuperSeal  
field RJ45/USB



dual flange  
receptacle

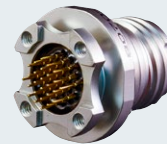
High-speed  
El Ochito  
octaxial  
contacts



Ultra high density .075" contact center mil-aero solution for size and weight reduction



straight and 90°  
receptacles



Dual-flange PCB  
receptacles



New Series  
806 for  
SWAMP-zone  
applications

SuperFly: the ultimate nanominiature tactical connector



straight and 90° QDC or threaded  
receptacles with mounting holes



high-speed datalink version  
with El Ochito® contacts

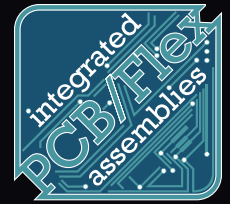
Series 89 circular nanominiature connectors



Threaded  
straight and 90°



Breakaway straight and 90°



The termination of flex and rigid flex assemblies to backplane and motherboard PCBs may be accomplished with a variety of interconnect technologies and flex design features. Glenair flex engineers have deep fluency in the maintenance and protection of signal continuity from the I/O interface to the board, including high-speed, matched impedance signal management, EMI/RFI shielding and so on.

### STEP 2: DEFINE STYLE OF PCB / FLEX TERMINATIONS



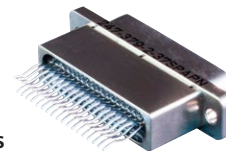
Thru-hole



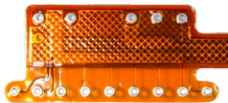
Surface mount



Pogo pin /  
spring-loaded contacts



Straddle  
mount



Nail head  
pins



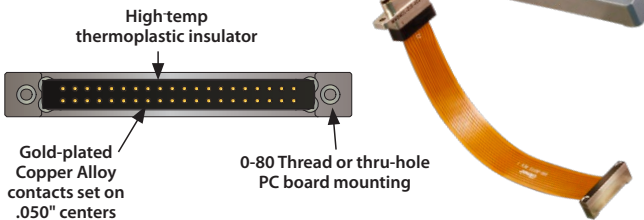
Direct  
termination



Encapsulating  
pot



ZIF (zero  
insertion force)



AlphaLink® board-level pogo-pin connectors and flex jumpers



Press-fit (compliant pin)  
board mounting



.0625" pitch contact spacing:  
highest available density

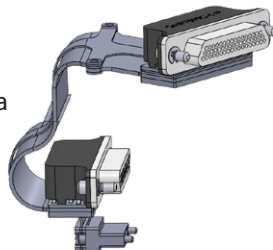


Polarized shells and keyed  
guide pin hardware

High-density, solder-free, board-to-board stackable connectors

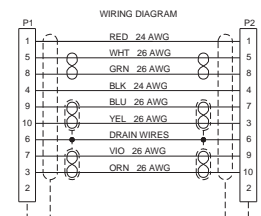
### STEP 3: DEFINE MECHANICAL SCHEMATIC

- Customer-supplied 3-D file to determine "keep out areas"
- "Napkin sketch" with rough idea of routing
- Customer-supplied 2-D DXF



### STEP 4: DEFINE ELECTRICALS

- To approximate layer count, we need a wiring diagram "schematic" complete with signal types, currents, and shielding requirements
- Used to determine ROM pricing

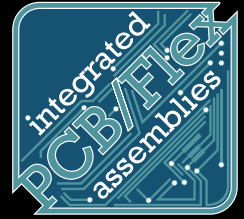


### STEP 5: DEFINE VALIDATION TEST REQUIREMENTS

Glenair offers complete circuit design and generation of PCB/flex fabrication data packages including component level documentation. Most flex customers specify a certain level of validation testing as a required part of the documentation package. Tests may include DWV/IR, continuity, impedance (eye pattern), and others.



# Design Service Information Form



**Electronic copy available upon request**  
 [see back of catalog for contact information]

Please fill in as much as possible. We understand that information will need to be modified / adjusted later during the design process.

Customer Name \_\_\_\_\_

Customer Address \_\_\_\_\_

Engineer / Point of Contact  
 Name, email, Phone Number \_\_\_\_\_

## GENERAL QUESTIONS

PCB P/N \_\_\_\_\_ Assembly P/N \_\_\_\_\_

Revision (1, 2... A, B...) \_\_\_\_\_

Title \_\_\_\_\_

DCN Number (when applicable) \_\_\_\_\_

Class 2	Class 3	RoHS Compliant	Yes	No
---------	---------	----------------	-----	----

Job Number \_\_\_\_\_

Where Used, and Program Name \_\_\_\_\_

Schematic Provided Yes No If Yes, Schematic P/N \_\_\_\_\_

Schematic Completed and Reviewed? Yes No Provide Part Geometries? Yes No

Provide Part Datasheets? Yes No Provide Net List in Xpedition Format Yes No

Design Rules from Customer Yes No *(If Yes, please list details in "Notes and Additional Instructions" section below)*

Will Require Gerber Files Yes No Silkscreen and Etch Required? Yes No

Glenair H/W in place of Existing H/W? Yes No Is Glenair H/W currently used? Yes No

## DESIGN / CONSTRUCTION

Design Type (Rigid, Flex, Rigid Flex, etc.) \_\_\_\_\_

Final Board Thickness (e.g. .062" ±.006") \_\_\_\_\_ Material and DK \_\_\_\_\_

Proposed Layer Count (may change) \_\_\_\_\_

Will This Design Utilize Stiffeners? Yes No If Yes, Type: \_\_\_\_\_

Proposed Finished Copper Weight (start foil +.001" after plating): \_\_\_\_\_

*Continued on next page...*



**DESIGN / CONSTRUCTION (continued)**

Board Outline Supplied in DXF and/or IDF Format?	Yes	No		
Dimensions Provided?	Yes	No	Connector Location Provided?	Yes No
Tooling Hole Locations Provided?	Yes	No	Tooling Holes Plated?	Yes No
Stiffener/Bend Locations Provided?	Yes	No	Height Restrictions/Keepouts Defined?	Yes No
Maximum and Minimum Lengths	_____			
Conformal Coating?	Yes	No	If Yes, Type:	_____
Testing Requirements	Yes	No	If Yes, Type:	_____

**TECHNOLOGY (HIGH SPEED, RF, EMI, SHIELDING, ETC.)**

Any High Current Lines (please define)

Controlled Impedance?	Yes	No	Controlled Impedance Value and $\pm$ Tolerance	_____
Matched Pairs/Lengths ?	Yes	No	Controlled Impedance Calculation Provided?	Yes No
Routing Constraints Received?	Yes	No		

**OUTPUT FILES / INSTRUCTIONS / DELIVERABLES**

Require Export Control Notes?	Yes	No	Require Schematic Files PDF	Yes	No
Require Fabrication/Assembly PDFs?	Yes	No	Require ODB++ File?	Yes	No
Require Gerber Files?	Yes	No	Require BOM?	Yes	No

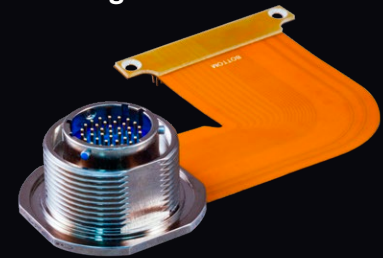
**SPECIAL NOTES AND ADDITIONAL INSTRUCTIONS**

# Integrated Flex, Rigid Flex, and PCB Assembly Production Lab

GLENDALE, CALIFORNIA

IPC 6012/6013 Class I, II, III, types 1–4  
ISO 9001, AS9100 Certified

Glenair Integrated PCB / Flex assembly production facilities are operated in accordance with commercial and military standards. Staff includes 200+ PCB and cable assemblers with Nadcap certification for special processes and ESD management.



- High-availability catalog components as well as custom design and manufacture
- No minimums
- We never obsolete parts

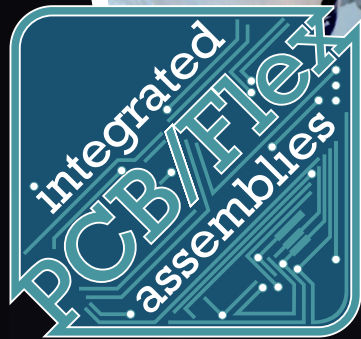
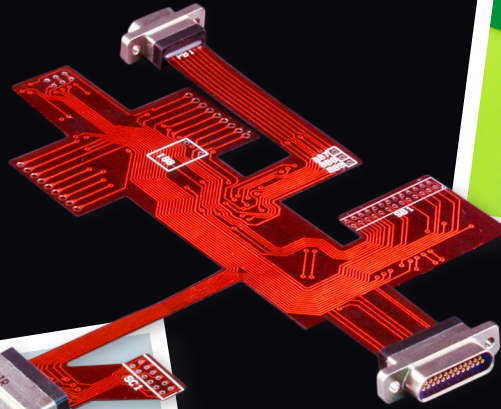


Automated Optical Inspection,  
Flying Probe Electrical Test, and  
Defluxing Washer





**Glenair's PCB/Flex interconnect team is housed together under one roof. From electrical design to computer-aided manufacturing and assembly, the team has a well-deserved reputation for on-time delivery of even the most complex PCB/Flex assemblies.**





# MISSION-CRITICAL INTERCONNECT SOLUTIONS

## Glenair, Inc.

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06492

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